

ABSTRACT

SUBSTRATE TRANSPORT AND FEEDING METHOD AND SUBSTRATE TRANSPORT AND FEEDING APPARATUS

A substrate transport and feeding method and a substrate transport and feeding apparatus according to the invention are characterized in that a substrate having a plurality of electronic components mounted on a surface thereof is transported to a position below an upper-die surface of a compression resin molding apparatus, and a substrate deformation correcting step is performed when a back surface of the substrate is adsorbed to and retained on the upper-die surface with the surface of the substrate looking downward. In the substrate deformation correcting step, compressed air is blown into a recessed housing portion of a substrate transport plate unit, and a center part of the substrate warping downward due to own weight is thereby pushed upward, so that the substrate with such a warp is corrected to be substantially horizontally straight.

FIG. 1